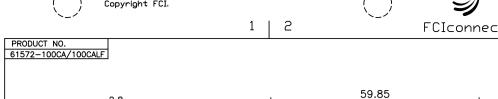
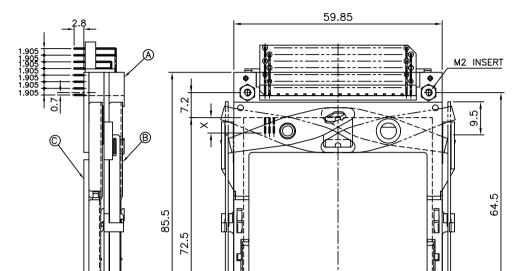
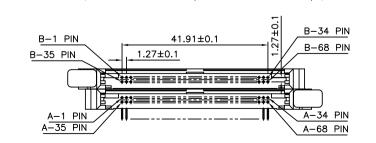
M2 NUT







51.4 54.2

31.5

1. EJECT FORCE: 3.5 Kg MAX.

2. EJECT TRAVEL: 8.0mm

3.1 PART (A) (HEADER ASS'Y) HOSUING : HIGH TEMPERATURE THERMOPLASTIC PIN : COPPER ALLOY

3.2 PART (B) AND (C) (EJECT MECHANISM ASS'Y) HOUSING : HIGH TEMPERATURE TERMOPLASTIC PLATE : STAINLESS EMI CONTACT: PHOSPHOR BRONZE

4. FINISH (PIN)

5.

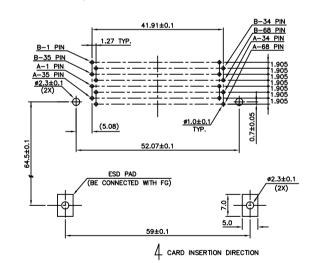
UNDER PLATING : 0.5 µm MIN. Ni CONTACT AREA : 0.1 µm MIN. GOLD OVER SOLDER TAIL (TIN LEAD OPTION): 2.5 µm MIN. Sn-Pb SOLDER TAIL (LEAD FREE OPTION): 2.5 µm MIN. PURE TIN

DIM"X"	4.25±0.1	3.5±0.1	5.0±0.1				
PIN MUMBER	OTHERS	36,67	1,17,34,35,51,68				

6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.

7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES

AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



ma	t'l. c	ode	?			sur	fac	e /	tol	era	nce	pro	jec	tio	pro	oduc	t f	amil	ly				
						15013	802	\vee	ISO	406 I	SD1101	d) _	1				PO	CMCI	Α			
ltr	ecn	nd		dα					unles	5S O	ther	wise-specifical title											
_ A_	T604	1 11	LS	08/	30/96	onc	angles 0.xx		(±0.3 MM			NARROW BODY FRONT EJECT							т				
В	T700)19	WL	01/	07/97	0.XX		±0.15		ł		=						·					
<u>c</u>	T902	279	WL	07/	23/99	O°±2	2. =	0.XXX±0.05			5	SCO	le1.	<u>5:1</u>	TYPE 1/2/3 EJECTOR ASS"								
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						chr	JOS	EPH	HSIA	08/3	30/96			7)				013	<i>3 / 2</i>	-			<i>P</i> 44
						app	d JE	NN TS	SAO	08/3	30/96		<u> </u>		tyr	e	Pro	duct	Cu	stom	ner	Draw	ing
she	eet [rev	'isio	nΕ	E	Е																	
ind	ex	she	et	1	2	3																	

DESCRIPTION form: A4mmXLc

ORDERING

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EJECT

EJECT

MECH ASS'Y

MECH ASS'Y HDR ASS'Y

USE THE FOLLOWING P/N FOR OFFICIAL

61571-00CA

95627-10CA

92821-000/000LF

P/N

8.25

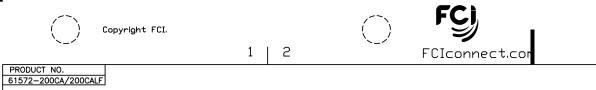
3.1

33.5

PDS: Rev :E3

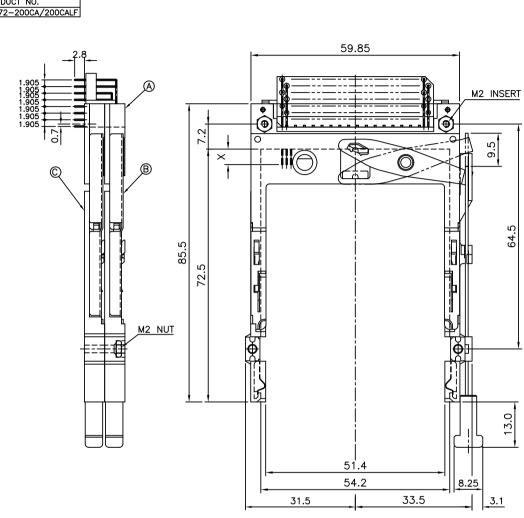
STATUS:Released

Printed: Sep 12 2013



3





B-1 PIN 41.91±0.1 B-35 PIN 1.27±0.1 A-1 PIN A-35 PIN

1

1. EJECT FORCE: 3.5 Kg MAX.

2. EJECT TRAVEL: 8.0mm
(3) MATERIAL

3.1 PART (A) (HEADER ASS'Y) HOUSING : HIGH TEMPERATURE THERMOPLASTIC

: COPPER ALLOY

3.2 PART B AND C (EJECT MECHANISM ASS'Y) HOUSING : HIGH TEMPERATURE THERMOPLASTIC PLATE : STAINLESS

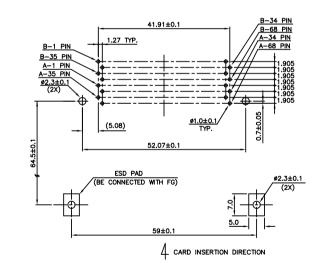
EMI CONTACT: PHOSPHOR BRONZE

4. FINISH (PIN)

UNDER PLATING :0.5µm MIN. NI CONTACT AREA :0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni SOLDER TAIL (TIN LEAD OPTION): 2.5µm MIN. Sn-Pb SOLDER TAIL (LEAD FREE OPTION): 2.5 µm MIN. PURE TIN

DIM"X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN MUMBER	OTHERS	36,67	1,17,34,35,51,68

6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



PDS: Rev :E 3

matíl code					surface / tolerance							projection product family											
						ISD1302 V ISD 406 ISD1101					ld	PCMCIA											
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Ε						مرد	angles 0.x			±0.3		мм			NARROW BODY FRONT EJECT						т I		
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						O°±	±2° 0.XXX±0.05			sco	ıle1.	5:1	TYPE 1/2/3 EJECTOR ASS'						ASS	Y			
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						eng	rjos	EPH	HSIA	08/3	0/96	F	C	. i				C 1 I	= 7	,			ا. ۸
						chr	JOS	EPH	HSIA	08/3	50/96	_		"				615) / Z	<u>-</u>			A4
						app	d JE	NN TS	SAO	08/3	50/96		7		typ	e	Pro	duct	Cu	stom	er	Draw	ing
she	et	rev	/isio	n																			
ind	eх	she	et																				

DESCRIPTION form: A4mmXLc

ORDERING

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EJEC1

MECH ASS'Y

MECH ASS'Y (A) HDR ASS'Y

USE THE FOLLOWING P/N FOR OFFICIAL

61571-00CA

95627-00CA

92821-000/000LI

P/N

STATUS:Released

Printed: Sep 1242013

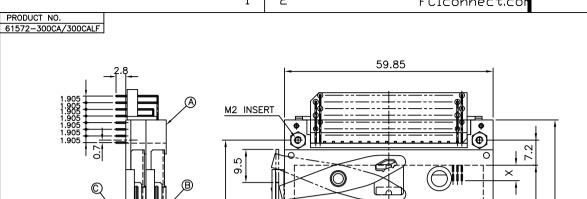
B-34 PIN

B-68 PIN

A-34 PIN

A-68 PIN

3



M2 NUT

М,

8.25

3.1

B-1 PIN

B-35 PIN

A-1 PIN

1

A-35 PIN

33.5

NOTES:

EJECT FORCE : 3.5 Kg MAX.

EJECT TRAVEL: 8.0mm

MATERIAL

3.1 PART (A) (HEADER ASS'Y) HOUSING: HIGH TEMPERATURE THERMOPLASTIC :COPPER ALLOY

3.2 PART (B) AND (C) (EJECT MECHANISM ASS'Y) HOUSING: HIGH TEMPERATURE THERMOPLASTIC

PLATE : STAINLESS EMI CONTACT: PHOSPHOR BRONZE

4. FINISH (PIN)

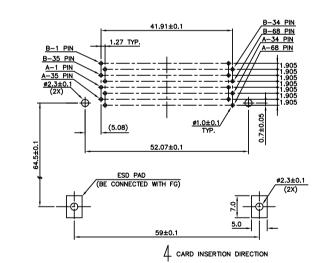
UNDER PLÁTING : 0.5 μm MIN. Ni CONTACT AREA : 0.1 μm MIN. GOLD OVER 0.5 μm MIN. Pd-Ni SOLDER TAIL (TIN LEAD OPTION): 2.5 µm MIN. Sn-Pb SOLDER TAIL (LEAD FREE OPTION): 2.5 µm MIN. PURE TIN

_			. ,					
5.	DIM"X"	4.25±0.1	3.5±0.1	5.0±0.1				
	PIN MUMBER	OTHERS	36,67	1,17,34,35,51,68				

6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES

AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008

8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



surface mat'l, code tolerance|projectionproduct family PCMCIA IS01302 ISD 406 ISD1101 specifie dtitle ltrecn nødredate tolerances unless other 0.X±0.3 angle & NARROW BODY FRONT EJECT 0.XX±0.15 TYPE 1/2/3 EJECTOR ASS'Y 0°±2° 0.XXX±0.05 scale1.5:1 sheet3of3 size SHIRLEY 08/30/96 dwg no engrjoseph HSIA 08/30/96 61572 chr joseph HSIA 08/30/96 appd Jenn TSAO type Product Customer Drawing 08/30/96 sheet revision

PDS: Rev :E 3

DESCRIPTION form: A4mmXLc

EJECT

EJECT MECH ASS'Y

MECH ASS'Y

HDR ASS'Y

ORDERING

0

USE THE FOLLOWING P/N FOR OFFICIAL

61571-10CA

95627-10CA

92821-000/000LF

P/N

2

B-34 PIN

B-68 PIN

A-34 PIN

A-68 PIN

index sheet

51.4

54.2

41.91±0.1

31.5

1.27±0.1

STATUS: Released

Printed: Sep 1242013